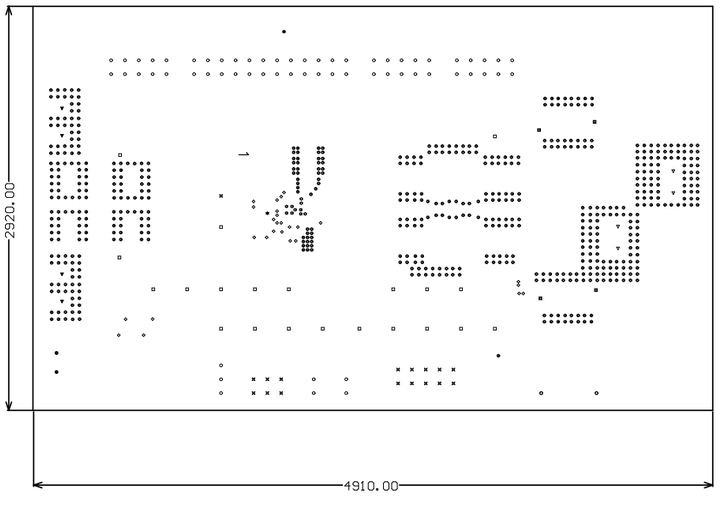
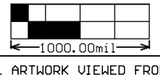
Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
☆	10	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
◇	27	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
◎	577	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
✱	2	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
⌘	17	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
○	61	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
✣	2	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
▣	4	53.15mil (1.350mm)	NPTH	Round	Top Layer - Bottom Layer	
▼	4	55.12mil (1.400mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	62.50mil (1.588mm)	PTH	Round	Top Layer - Bottom Layer	
□	21	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
	731 Total					

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.50mil	3.3	
1	Top Layer		2.76mil		
	Dielectric 1	FR-4 High TG	7.09mil	4.2	
2	GND Layer 2		2.56mil		
	Dielectric 2	FR-4 High TG	3.94mil	4.2	
3	Signal Layer 3		2.56mil		
	Dielectric 3	FR-4 High TG	8.07mil	4.2	
4	PWR Layer 4		2.56mil		
	Dielectric 5	FR-4 High TG	3.94mil	4.2	
5	PWR Layer 5		2.56mil		
	Dielectric 4	FR-4 High TG	8.07mil	4.2	
6	Signal Layer 6		2.56mil		
	Dielectric 6	FR-4 High TG	3.94mil	4.2	
7	GND Layer 7		2.56mil		
	Dielectric 8	FR-4 High TG	7.09mil	4.2	
8	Bottom Layer		2.76mil		
	Bottom Solder	Solder Resist	0.50mil	3.3	
	Bottom Overlay				



Drill Drawing



DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2920MIL X 4770MIL

Number of Layers : 8
MIN. TRACK WIDTH: 10 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 20 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 64 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [X] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [ ] 1MIL [X] OTHER 1.9MIL
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [X] MATTE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: TPS546E25EVM-1PH
DESIGNED FOR: Public Release
FILE NAME: SR036.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SR036	REV: A	SUN REV: Not in version control
LAYER NAME = M2 Solder Mask Top Dimensions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 10/14/2025 12:10:42 PM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
Caleb Perez	Caleb Perez
SCALE: 0.91	ALTIUM DESIGNER VERSION: 23.1.1.15